

RELIABILITY REPORT

FOR

MAX20734EPL+

PLASTIC ENCAPSULATED DEVICES

February 9, 2017

MAXIM INTEGRATED

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Conclusion

The MAX20734EPL+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX20734 is a fully integrated, highly efficient switching regulator with PMBus™ for applications operating from 4.5V to 16V and requiring up to 40A (max) load. This single-chip regulator provides extremely compact, highefficiency power-delivery solutions with high-precision output voltages and excellent transient response for networking, datacom, and telecom equipment. The IC offers a broad range of programmable features through either the PMBus or a capacitor and resistor connected to a dedicated programming pin. Using this feature, the operation can be optimized for a specific application, reducing the component count and/or setting appropriate trade-offs between the regulator's performance and system cost. Ease of programming enables using the same design for multiple applications. The IC includes protection and telemetry features. Positive and negative cycle-by-cycle overcurrent protection and overtemperature protection ensure a rugged design. Input undervoltage lockout shuts down the device to prevent operation when the input voltage is out of specification. A status pin provides an output signal to show that the output voltage is within range and the system is regulating.



II. Manufacturing Information

A. Description/Function: 40A INTEGRATED, STEP-DOWN SWITCHING REGULATOR with PMBus

B. Process: TS18
C. Fabrication Location: Taiwan
D. Assembly Location: Thailand
E. Date of Initial Production: June 24, 2016

III. Packaging Information

A. Package Type: FCQFN
B. Lead Frame: Copper

C. Lead Finish: 100% matte TinD. Die Attach: Conductive

E. Bondwire: SAC105 (9.8 mil dia.)F. Mold Material: Epoxy with silica filler

G. Assembly Diagram: #05-0839
H. Flammability Rating: Class UL94-V0

I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C

Level 1

J. Single Layer Theta Ja: N/A°C/W
K. Single Layer Theta Jc: N/A°C/W
L. Multi Layer Theta Ja: 12°C/W
M. Multi Layer Theta Jc: 0.42°C/W

IV. Die Information

A. Dimensions: 88.5827X303.1495 mils

B. Passivation: Si₃N₄/SiO₂
 C. Interconnect: Al/0.5%Cu
 D. Backside Metallization: None

E. Minimum Metal Width: 0.23 microns (as drawn)F. Minimum Metal Spacing: 0.23 microns (as drawn)

G. Isolation Dielectric: SiO₂H. Die Separation Method: Wafer Saw



V. Quality Assurance Information

A. Quality Assurance Contacts: Eric Wright (Reliability Engineering)

Brian Standley (Manager, Reliability) Bryan Preeshl (Vice President of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.

0.1% for all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppmD. Sampling Plan: Mil-Std-105D

3. = 13.7 F.I.T. (60% confidence level @ 25°C)

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate () is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

$$\lambda = 13.7 \times 10^{-9}$$

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The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the TS18 Process results in a FIT Rate of 0.1@ 25C and 1.9@ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The VT36-0 die type has been found to have all pins able to withstand an HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-100mA and overvoltage per JEDEC JESD78.



Table 1Reliability Evaluation Test Results

MAX20734EPL+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (N	Note 1)				
	Ta = 135C	DC Parameters	80	0	
	Biased	& functionality			
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.